公TDK 积层贴片陶瓷片式电容器 C1608JB1H684K080AB

RoHS Reach Halogen Free Pb Free

交货型号	C1608JB1H684KT****	
用途	一般等级	
特点	General 一般(~75V)	
系列	C1608 [EIA 0603]	6
状态	▲ 量产体制(新设计非推荐)	B

	尺寸
长度(L)	1.60mm ±0.10mm
宽度(W)	0.80mm ±0.10mm
厚度(T)	0.80mm ±0.10mm
端子宽度 (B)	0.20mm Min.
端子间隔(G)	0.30mm Min.
推荐焊盘布局 (PA)	0.70mm to 1.00mm(Flow Soldering)
1世行/产血/叩/미 (L f.)	0.60mm to 0.80mm(Reflow Soldering)
推荐焊盘布局(PB)	0.80mm to 1.00mm(Flow Soldering)
]世代/序竝/仰/问 (LD)	0.60mm to 0.80mm(Reflow Soldering)
推荐焊盘布局(PC)	0.60mm to 0.80mm(Flow Soldering)
1世行/干血114/月116/	0.60mm to 0.80mm(Reflow Soldering)

电气特性		
电容	$680 nF \pm 10\%$	
额定电压	50VDC	
温度特性	JB(±10%)	
	7.5%	
	735ΜΩ	

	其他
焊接方法	流体
冲按刀 法	回流
AEC-Q200	NO
	纸编带(180mm卷筒)
包装个数	4000pcs

 $!\ \mbox{Images}$ are for reference only and show exemplary products.

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! All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

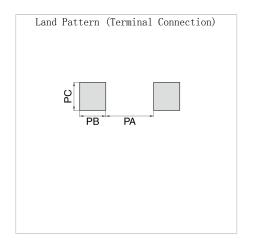
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Associated Images



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